Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	10/624601.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 11:08
S2	431	(imperfect adj connection) or (discontinued adj areas)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 13:33
S3	1	S1 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 14:55
S4	239	345/206.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 11:21
S5	10	takenaka-yuuichi.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 12:19
S7	5855714	gap or hole or (imperfect near connection) or space	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 12:21
S8	265369	S6 and S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:20
S9	82	S8 and S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 12:28
S10	419089	resin and conduct$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 12:28

S11	23	S9 and S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 12:58
S12	186826	thermal near (expansion or expanding or expand)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 12:59
S13	8	S12 and S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 13:00
S14	2	S11 and S12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 13:08
S15	1517	349/158.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 13:08
S16	270	S15 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 13:19
S17	1372	349/155.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 13:20
S18	303	S17 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 13:20
S19	7	S2 and "349".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 13:33

S20	52081	insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 14:55
S21	1	S1 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 14:57
S22	5855714	gap or hole or (imperfect near connection) or space	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:21
S23	573394	(insulat$3 near3 (substrate or layer or part))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:20
S24	265369	S22 and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:20
S25	6076752	gap or hole or (imperfect near connection) or space or slit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:21
S26	269060	S25 and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ;.IBM_TDB	OR	ON	2005/11/14 17:21
S27	1517	349/158.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:22
S28	188	S26 and S27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:39

S29	253878	PCB or (printed adj circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:40
S30	18476	S29 and S25 and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:40
S31	961	349/84.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:40
S32	1	S30 and S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:41
S33	1372	349/155.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:41
S34	11	S30 and S33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/14 17:41
S35	239	345/206.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:07
S36	961	349/84.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:07
S37	1373	349/155.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:07

S38	1517	349/158.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:20
S39	1137	349/138.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:20
S40	5856777	gap or hole or (imperfect near connection) or space	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 15:54
S41	609	S39 and S40	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:20
S42	253972	PCB or (printed adj circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:32
S43	58501	S40 same S42	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:33
S44	8	S43 and S39	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:42
S45	377	349/142.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 14:16
S46	327	349/150.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/15 08:45

S47	2	S43 and S45	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 08:46
S48	53	S43 and S46	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 08:46
S50	271	349/151.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 09:35
S51	253972	PCB or (printed adj circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:59
S52	158030	resin same (conductive or conductor or conducting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:41
S53	5146	S52 same S51	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:42
S54	37745	"349".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:42
S55	51	S53 and S54	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:42
S56	6834033	gap or hole or (imperfect near connection) or space or slot or slit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:54

S57	5613	(multi-layered or (multi adj layered) or (multiple adj layered) or multi-layer or (multi adj layer) or (multiple adj layer)) with S51	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:56
S58	1669	S56 same S57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:57
S59	11	S54 and S58	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:57
S60	132994	S51 and S56	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:59
S61	1037	S60 and S54	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 16:00
S62	117	S61 and S52	USPAT	OR	ON	2005/11/15 16:06
S63	370557	Sharp Kabushiki Kaisha.As.	USPAT	OR	ON	2005/11/15 16:18
S64	53433	S63 and slot	USPAT	OR	ON	2005/11/15 16:18
S65	80	S63 and S58	USPAT	OR	ON	2005/11/15 16:19
S66	2	S65 and "349".clas.	USPAT	OR	ON	2005/11/15 16:20
S67	79838	thermal adj expan$5	USPAT	OR	ON	2005/11/15 16:33
S68	14320	"349".clas.	USPAT	OR	ON	2005/11/15 16:20
S69	544	S67 and S68	USPAT	OR	ON	2005/11/15 16:20
S70	466	S69 and S56	USPAT	OR	ON	2005/11/15 16:22
S71	137	S67 and S52 and S57 and S56	USPAT	OR	ON	2005/11/15 16:34
S72	7	("4506004" | "4715117" | "4728568" | "5591353" | "6272745" | "6276055" | "6631838").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/15 16:36
S73	253972	PCB or (printed adj circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 08:18

S74	158030	resin same (conductive or conductor or conducting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 08:18
S75	6834033	gap or hole or (imperfect near connection) or space or slot or slit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:44
S76	5613	(multi-layered or (multi adj layered) or (multiple adj layered) or multi-layer or (multi adj layer) or (multiple adj layer)) with S73	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:09
S77	79838	thermal adj expan$5	USPAT	OR	ON	2005/11/16 08:18
S78	137	S77 and S74 and S76 and S75	USPAT	OR	ON	2005/11/16 10:35
S79	21608	TCP or (tape adj carrier adj package) or T-C-P	USPAT	OR	ON	2005/11/16 08:25
S80	5	S74 and S76 and S75 and S77 and S79	USPAT	OR	ON	2005/11/16 08:28
S81	239	345/206.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 13:23
S82	8	S81 and S77	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 08:27
S83	9	S74 and S76 and S75 and S79	USPAT	OR	ON	2005/11/16 08:28
S84	271	349/151.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 09:55
S85	424	349/152.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 10:03
S86	5764619	hannstar display corp.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 10:03

S87	17	S86 and S78	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 10:17
S89	1	09/204130.app.	USPAT	OR	ON	2005/11/16 10:19
S90	53	("3913219" | "3947956" | "4416914" | "4555745" | "4566186" | "4632845" | "4774634" | "4808434" | "4870746" | "5225969" | "5298687" | "5305523" | "5347258" | "5354599" | "5384434" | "5428190" | "5502889" | "5527998" | "5599595" | "5688584" | "5716663" | "5727310" | "5747222" | "5758575" | "5763058" | "5814366").PN. OR ("6021050").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/16 10:21
S91	2990	428/209.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/16 10:26
S92	19	S91 and S78	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/16 10:21
S93	1065	428/194.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/16 10:26
S94	3741037	S75	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/16 10:26
S95	503	S75 and S93	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/16 10:31
S96	2	09/136201.app.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/16 10:31
S97	4	S78 and "349".clas.	USPAT	OR	ON	2005/11/16 10:37
S98	54	S79 and (prevent$3 with S77)	USPAT	OR	ON	2005/11/16 10:46
S99	3236	438/106.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 10:48
S100	59	S99 and S76 and S75	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 10:49

S101	86	multiplelayer or multiplelayering with S73	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:10
S102	48	S101 and S75	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:26
S103	14007	prevent$3 same S77	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:26
S104	11222	S103 and S75	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:32
S105	64	S104 and S76	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:27
S106	4584231	(imperfect near connection) or space or slot or slit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:44
S107	2530	S76 and S106	US-PGPUB; USPAT; USOCR; . EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:44
S108	491	S107 and S74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 11:45
S109	573537	(insulat$3 near3 (substrate or layer or part))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/16 12:30

S110	119	S109 and S79 and S77	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 12:30
S111	239	345/206.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 13:18
S112	1	"6738123".pn. and insulat$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 13:24
S113	2	("6738123").URPN.	USPAT	OR	ON	2005/11/16 13:24
S114	6	("5745202" | "5969780" | "6198051" | "6198521" | "6369867" | "6573954").PN. OR ("6870589").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/16 13:31
S115	52097	insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 13:35
S116	7	S115 and S79 and S76 and S75	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 13:38
S117	18	("6121553").URPN.	USPAT	OR	ON	2005/11/16 14:22
S118	1	S116 and (semiconductor adj chip)	USPAT	OR	ON	2005/11/16 14:23
S119	0	10/624601.app.	USPAT	OR	ON	2005/11/16 14:24
S120	1	10/624601.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 14:24
S121	1	S120 and (semiconductor adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 14:33
S122	1	resin and 09/204130.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/16 14:33